

L Number	Hits	Search Text	DB	Time stamp
1	41436	resist\$3 same heat\$3 same method	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 15:45
2	360	(resist\$3 same heat\$3 same method) and thermal adj spray\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 15:46
3	232	((resist\$3 same heat\$3 same method) and thermal adj spray\$3) and gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 15:46
4	11	((((resist\$3 same heat\$3 same method) and thermal adj spray\$3) and gas) and metallic adj component	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:04
5	12	((((resist\$3 same heat\$3 same method) and thermal adj spray\$3) and gas) and metallic near2 component	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 15:50
6	41	((((resist\$3 same heat\$3 same method) and thermal adj spray\$3) and gas) and metal\$3 near2 component	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 15:51
8	15	(((((resist\$3 same heat\$3 same method) and thermal adj spray\$3) and gas) and metal\$3 near2 component) and zirconium) and molybdenum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 15:52
7	26	(((((resist\$3 same heat\$3 same method) and thermal adj spray\$3) and gas) and metal\$3 near2 component) and zirconium	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 15:57
9	16	((((resist\$3 same heat\$3 same method) and thermal adj spray\$3) and gas) and control\$3 near2 resist\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:15
10	19	((resist\$3 same heat\$3 same method) and thermal adj spray\$3) and control\$3 near2 resist\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:04
11	671	(resist\$3 same heat\$3 same method) and control\$3 near resist\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:43
12	141	((resist\$3 same heat\$3 same method) and control\$3 near resist\$5) and spray\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:04

13	2	((resist\$3 same heat\$3 same method) and control\$3 near resist\$5) and spray\$3) and metallic adj component	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:05
14	25	((resist\$3 same heat\$3 same method) and control\$3 near resist\$5) and spray\$3) and 219/\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:05
15	17	((((resist\$3 same heat\$3 same method) and control\$3 near resist\$5) and spray\$3) and 219/\$) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:29
16	2	(((((resist\$3 same heat\$3 same method) and control\$3 near resist\$5) and spray\$3) and 219/\$) and substrate) and reactant adj gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:16
17	112	((resist\$3 same heat\$3 same method) and control\$3 near resist\$5) and spray\$3) and manufact\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:30
18	56	((resist\$3 same heat\$3 same method) and control\$3 near resist\$5) and spray\$3) and manufact\$5 with method	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:37
19	14	"5039840"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:38
20	1	"5039840" and control\$3 near resist\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:39
21	78	(resist\$3 same heat\$3 same method) and control\$3 near resistivity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:46
22	2	(resist\$3 same heat\$3 same method) and control\$3 near resistivity with gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:48
23	0	(resist\$3 same heat\$3 same method) and control\$3 near resistivity with react\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 17:03
24	5	(resist\$3 same heat\$3 same method) and control\$3 near resistivity same gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:48

25	18	(resist\$3 same heat\$3 same method) and control\$3 near resistivity with (oxide or nitride or carbide or boride)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 17:09
26	11	((resist\$3 same heat\$3 same method) and control\$3 near resistivity with (oxide or nitride or carbide or boride)) and deposit\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 17:09